ABSTRACT

METHOD AND APPARATUS FOR CONDUCTING SHEAR TESTS ON INTERCONNECT BONDS

A shear test is conducted on an interconnect bond formed on a surface of an electronic device by first determining a profile of the surface, and based on the determined profile, determining a shearing path which is at a substantially constant distance from the profile of the surface for a shear test tool to conduct the shear test on the interconnect bond. The shear test tool is then guided to move along the determined shearing path to measure a shear force of the interconnect bond.

[FIG. 1A]